



Vout1: +15V @ 600mA

Vout2: -15V @ 600mA

Change Weightage Feedback resistance to chnage the output .
 In order to reduce Drop across LDO , the Output Voltageson Bipolar supply was reduced to 12.5V and -13V .
 R10=51k and R8=24.3K

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H1 NY PMS 440 0025 PH H2 NY PMS 440 0025 PH H3 NY PMS 440 0025 PH H4 NY PMS 440 0025 PH

H5 1902C H6 1902C H7 1902C H8 1902C

H9 SJ-5303 (CLEAR) H10 SJ-5303 (CLEAR) H11 SJ-5303 (CLEAR) H12 SJ-5303 (CLEAR)

FID1 FID2 FID3 FID4 FID5 FID6

PCB Number: PMP10651
PCB Rev: E1

PCB LOGO
Texas Instruments

PCB LOGO
Pb-Free Symbol

PCB LOGO
FCC disclaimer

You should delete the nylon screws/standoffs and/or the bumpers as needed for your design (or substitute other parts from Hardware.IntLib). Bumpers are cheaper, but provide less clearance.

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You can delete this note too.

Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

LBL1
PCB Label
Size: 0.65" x 0.20"

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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Number: PMP10651	Rev: E1	Designed for: Public Release	Mod. Date: 4/20/2015
SVN Rev: Not in version control	Assembly Variant: [No Variations]	Project Title: Synchronous Split Supply	Sheet Title:
Drawn By:	File: PMP10651_Hardware_SchDoc	Sheet: 1 of 1	Size: B
Engineer: Ambresh Tripathi	Contact: http://www.ti.com/support	http://www.ti.com	

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